Compliant with IEC 62474/ D9.00

Semiconductor Device Type: JMA 008 VDFN 3x3x0.9mm NiPdAu			Termination Base Alloy: Copper Alloy (Cu)			Package Homogeneous Materials: 8.1 Electronics (e.g. pc boards, displays)				J-STD-609A Product Marking and/or Pkg. Labeling e4
Basic Substance	CAS Number	"Contained In" Sub-Component	% Total Weight	mg/part	ppm	11.51	(mg) Total	Mold Compound	% ot Total Weight	50.28
Silica, fused	60676-86-0	Mold Compound	45.252	10.363	452,520		Silica, fused	60676-86-0	90.00	
Epoxy Resin	Trade Secret	Mold Compound	2.439	0.558	24,386		Epoxy Resin	Trade Secret	4.85	
Phenolic Resin	Trade Secret	Mold Compound	2.439	0.558	24,386		Phenolic Resin	Trade Secret	4.85	
Carbon Black	1333-86-4	Mold Compound	0.151	0.035	1,508		Carbon Black	1333-86-4	0.30	
Copper Iron	7440-50-8 7439-89-6	Lead Frame Lead Frame	40.132 0.060	9.190 0.014	401,315 603	0.04	() T-(-1	Total	100.00 % of Total Weight	40.00
Phosphorous	7723-14-0	Lead Frame	0.060	0.014	161	9.21	(mg) Total Copper	Lead Frame 7440-50-8	% of Total Weight 99.78	40.22
Zinc (Metal)	7440-66-6	Lead Frame	0.016	0.004	121		Copper	7440-50-8 7439-89-6	99.78 0.15	
Silver	7440-00-0	Die Attach	1.009	0.003	10.087		Phosphorous	7723-14-0	0.04	
Epoxy resin	68475-94-5	Die Attach	0.262	0.060	2.620		Zinc (Metal)	7440-66-6	0.03	
Copper(II) oxide	1317-38-0	Die Attach	0.039	0.009	393	ı	Zino (motal)	Total	100.00	
Silicon	7440-21-3	Chip (Die)	5.890	1.349	58,900	0.30	(mg) Total	Die Attach	% of Total Weight	1.31
Gold	7440-57-5	Wire Bond	0.490	0.112	4.900		Silver	7440-22-4	77.00	
Nickel	7440-02-0	Plating on external leads (pins)	1.666	0.381	16,657		Epoxy resin	68475-94-5	20.00	
Palladium	7440-05-3	Plating on external leads (pins)	0.138	0.032	1,377		Copper(II) oxide	1317-38-0	3.00	
i alladiditi		Disting an automal loads (nins)	0.007	0.001	65			Total	100.00	
Gold	7440-57-5	Plating on external leads (pins)	0.00.	0.001						
	7440-57-5	TOTALS:	100.000	22.900	1,000,000	1.35	Total (mg)	Chip (Die)	% of Total Weight	5.89
Gold	0.0229	g Total Mass	100.000	22.900	1,000,000	1.35	Total (mg) Doped Silicon	Chip (Die) 7440-21-3	100.00	5.89
Gold	0.0229 materials comply w	TOTALS: g Total Mass th EU Directives: 2002/95/EC (27 January 2003) &	100.000	22.900	1,000,000	1.35		Chip (Die)		5.89
Gold conductor device and its homogenous EU (31 March 2015) and 2002/53/EC (En	0.0229 materials comply w d-of-Life Vehicles (E	TOTALS: g Total Mass th EU Directives: 2002/95/EC (27 January 2003) &	100.000 Directive 2011/	22.900 65/EU (08 Jun	1,000,000	0.11		Chip (Die) 7440-21-3	100.00	5.89 0.49
Gold conductor device and its homogenous EU (31 March 2015) and 2002/53/EC (En- ce with the above EU Directives has been cal substance is absent from the list ab Technology Incorporated's knowledge	0.0229 materials comply w d-of-Life Vehicles (E en verified via interriove, the chemical s and belief as of the	TOTALS: g Total Mass th EU Directives: 2002/95/EC (27 January 2003) & ELV) without exemption (zero)	100.000 Directive 2011/ nalytical test daniconductor deto believe that	22.900 65/EU (08 Jun eta. vice and, to th he unavoidabl	1,000,000 ne 2011) and e best of		Doped Silicon	Chip (Die) 7440-21-3 Total Wire Bond 7440-57-5	100.00 100.00 % of Total Weight	
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